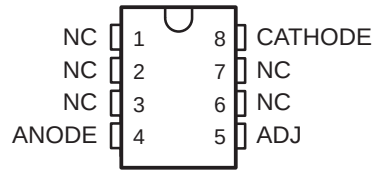
LM236-2.5, LM336-2.5, LM336B-2.5
2.5-V INTEGRATED REFERENCE CIRCUITS

SLVS063E − NOVEMBER 1988 − REVISED OCTOBER 2003

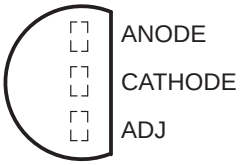
- **Low Temperature Coefficient**
- **Wide Operating Current . . . 400 μA to 10 mA**
- **0.27-Ω Dynamic Impedance**
- **±1% Tolerance Available**
- **Specified Temperature Stability**
- **Easily Trimmed for Minimum Temperature Drift**
- **Fast Turnon**

D PACKAGE
(TOP VIEW)



NC − No internal connection

LM336-2.5, LM336B-2.5 . . . LP PACKAGE
(TOP VIEW)



description/ordering information

The LM236-2.5, LM336-2.5, and LM336B-2.5 integrated circuits are precision 2.5-V shunt regulator diodes. These reference circuits operate as low-temperature-coefficient 2.5-V Zener diodes with a 0.2-Ω dynamic impedance. A third terminal provided on the circuit allows the reference voltage and temperature coefficient to be trimmed easily.

The series is useful as precision 2.5-V low-voltage references (V_Z) for digital voltmeters, power supplies, or operational-amplifier circuitry. The 2.5-V voltage reference makes it convenient to obtain a stable reference from 5-V logic supplies. Devices in this series operate as shunt regulators, and can be used as either positive or negative voltage references.

The LM236-2.5 is characterized for operation from −25°C to 85°C. The LM336-2.5 and LM336B-2.5 are characterized for operation from 0°C to 70°C.

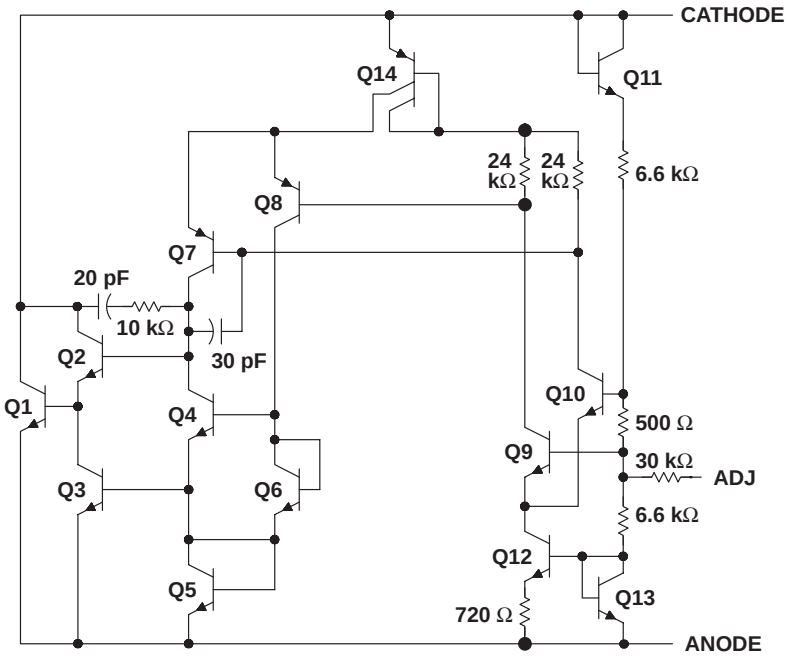
ORDERING INFORMATION

T_A	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
0°C to 70°C	SOIC (D)	Tube of 75	LM336D-2-5	336-25
		Reel of 2500	LM336DR-2-5	
		Tube of 75	LM336BD-2-5	336B25
		Reel of 2500	LM336BDR−2-5	
	TO-226 / TO-92 (LP)	Bulk of 1000	LM336LP-2-5	336-25
		Reel of 2000	LM336LPR-2-5	
		Bulk of 1000	LM336BLP-2-5	336B25
		Reel of 2000	LM336BLPR-2-5	
−25°C to 85°C	SOIC (D)	Tube of 75	LM236D-2-5	236-25
		Reel of 2500	LM236DR-2-5	

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

symbol

schematic diagram



NOTE A: All component values are nominal.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Reverse current, I_R	20 mA
Forward current, I_F	10 mA
Package thermal impedance, θ_{JA} (see Notes 1 and 2): D package	97°C/W
LP package	140°C/W
Operating virtual junction temperature, T_J	150°C
Storage temperature range, T_{stg}	−65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. Maximum power dissipation is a function of $T_J(max)$, θ_{JA}, and T_A. The maximum allowable power dissipation at any allowable ambient temperature is $P_D = (T_J(max) - T_A)/\theta_{JA}$. Operating at the absolute maximum T_J of 150°C can impact reliability.
2. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions

			MIN	MAX	UNIT
T_A	Operating free-air temperature	LM236-2.5	−25	85	°C
		LM336-2.5, LM336B-2.5	0	70	

electrical characteristics at specified free-air temperature (unless otherwise noted)

PARAMETER		TEST CONDITIONS		T_A†	LM236-2.5			LM336-2.5			UNIT
					MIN	TYP	MAX	MIN	TYP	MAX	
V_Z	Reference voltage	I_Z = 1 mA	LM236, LM336	25°C	2.44	2.49	2.54	2.39	2.49	2.59	V
			LM336B					2.44	2.49	2.54	
$\Delta V_{Z(\Delta T)}$	Change in reference voltage with temperature	V_Z adjusted to 2.490 V, I_Z = 1 mA		Full range		3.5	9		1.8	6	mV
$\Delta V_{Z(\Delta I)}$	Change in reference voltage with current	I_Z = 400 μA to 10 mA		25°C		2.6	6		2.6	10	mV
				Full range		3	10		3	12	
$\Delta V_{Z(\Delta t)}$	Long-term change in reference voltage	I_Z = 1 mA		25°C		20			20		ppm/khr
z_z	Reference impedance	I_Z = 1 mA, f = 1 kHz		25°C		0.2	0.6		0.2	1	W
				Full range		0.4	1		0.4	1.4	

† Full range is −25°C to 85°C for the LM236-2.5 and 0°C to 70°C for the LM336-2.5 and LM336B-2.5.

TYPICAL CHARACTERISTICS

CHANGE IN REFERENCE VOLTAGE vs REFERENCE CURRENT

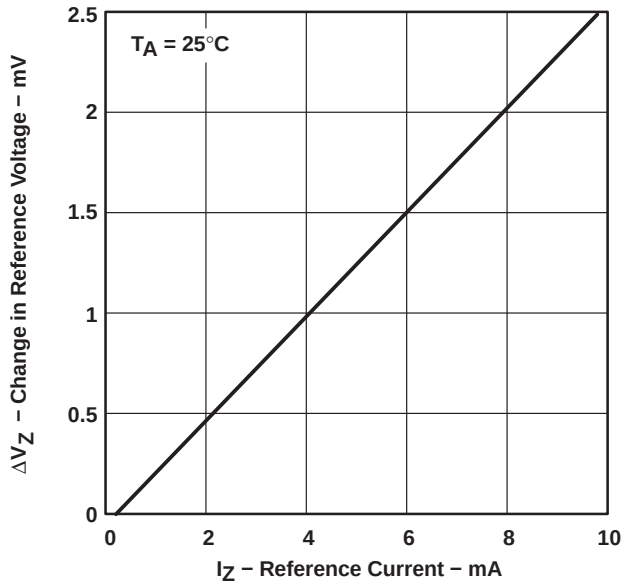


Figure 1

NOISE VOLTAGE vs FREQUENCY

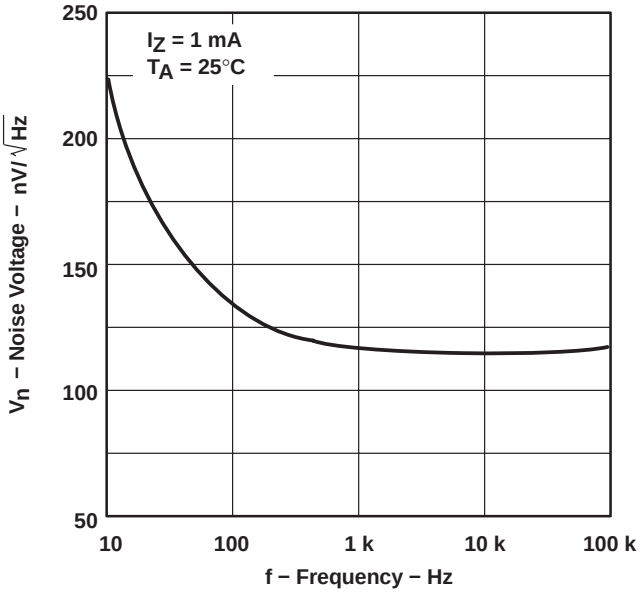


Figure 2

REFERENCE IMPEDANCE vs FREQUENCY

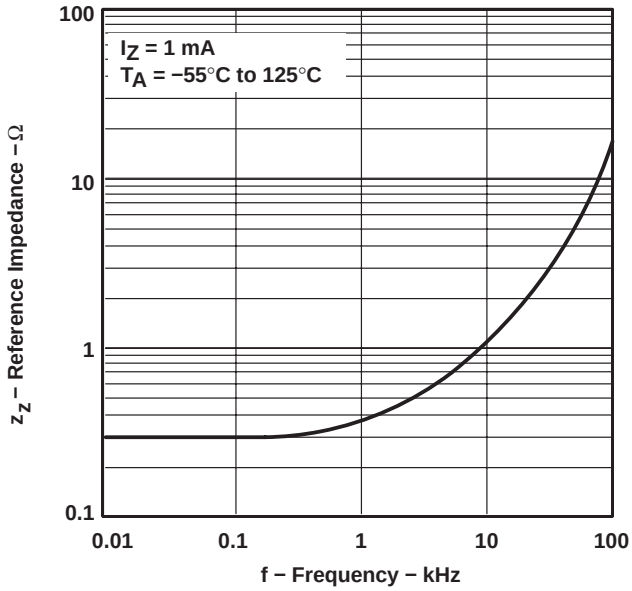


Figure 3

APPLICATION INFORMATION

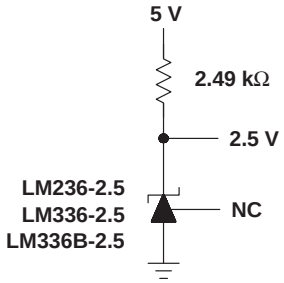


Figure 4. 2.5-V Reference

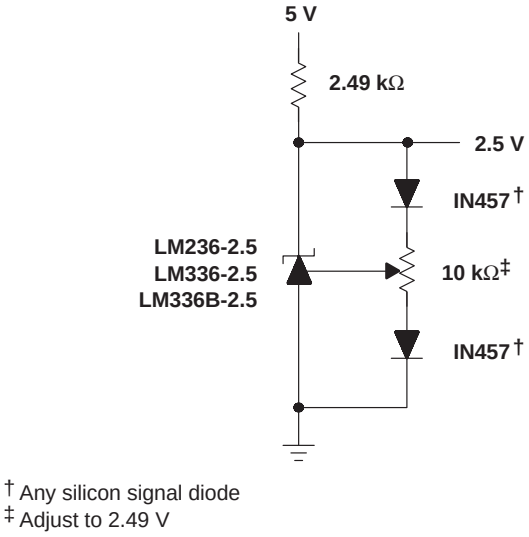


Figure 5. 2.5-V Reference With Minimum Temperature Coefficient

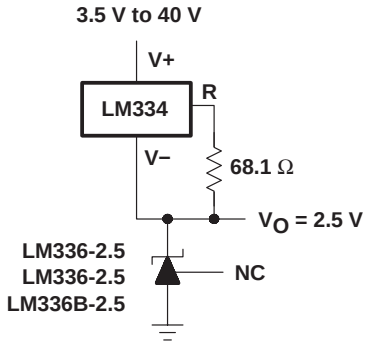


Figure 6. Wide-Input-Range Reference

PACKAGING INFORMATION

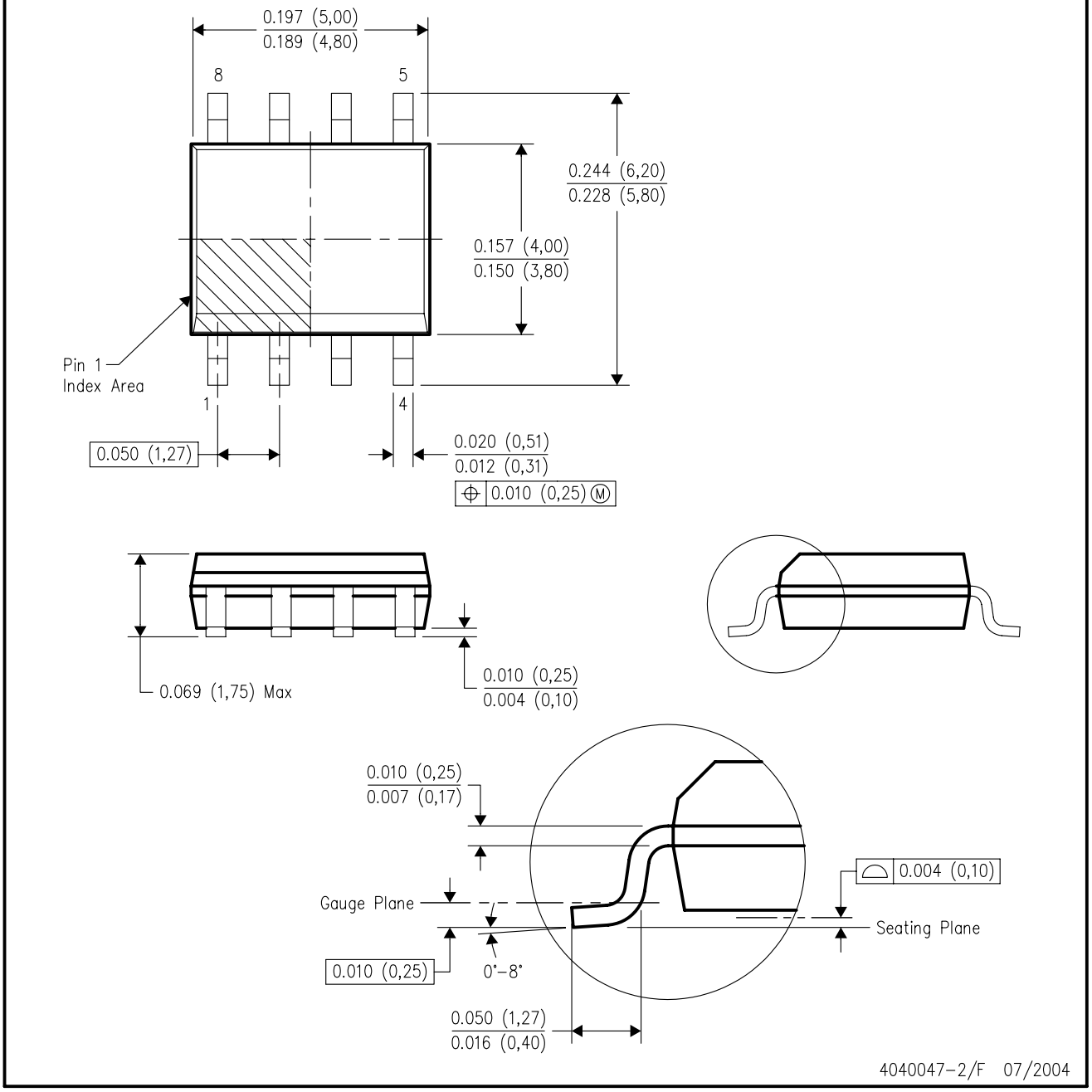
Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)
LM236D-2-5	ACTIVE	SOIC	D	8	75	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
LM236DR-2-5	ACTIVE	SOIC	D	8	2500	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
LM236LP-2-5	OBSOLETE	TO-92	LP	3		None	Call TI	Call TI
LM336BD-2-5	ACTIVE	SOIC	D	8	75	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
LM336BDR-2-5	ACTIVE	SOIC	D	8	2500	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
LM336BLP-2-5	ACTIVE	TO-92	LP	3	1000	None	CU SNPB	Level-NC-NC-NC
LM336BLPR-2-5	ACTIVE	TO-92	LP	3	2000	None	CU SNPB	Level-NC-NC-NC
LM336D-2-5	ACTIVE	SOIC	D	8	75	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
LM336DR-2-5	ACTIVE	SOIC	D	8	2500	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
LM336LP-2-5	ACTIVE	TO-92	LP	3	1000	None	CU SNPB	Level-NC-NC-NC
LM336LPR-2-5	ACTIVE	TO-92	LP	3	2000	None	CU SNPB	Level-NC-NC-NC

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - May not be currently available - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
None: Not yet available Lead (Pb-Free).
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Green (RoHS & no Sb/Br): TI defines "Green" to mean "Pb-Free" and in addition, uses package materials that do not contain halogens, including bromine (Br) or antimony (Sb) above 0.1% of total product weight.

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDECindustry standard classifications, and peak solder temperature.

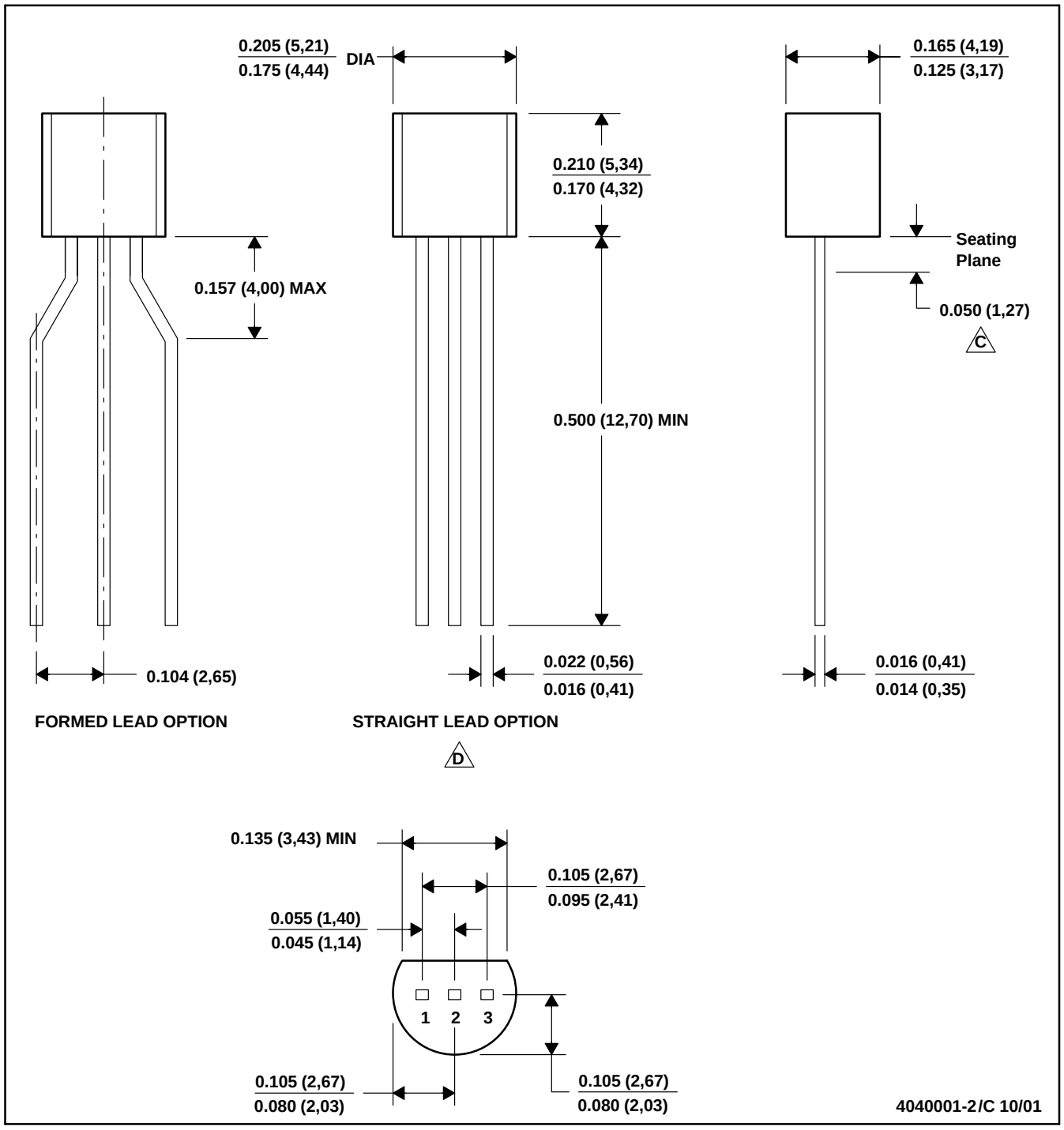
D (R–PDSO–G8) PLASTIC SMALL–OUTLINE PACKAGE



NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
D. Falls within JEDEC MS–012 variation AA.

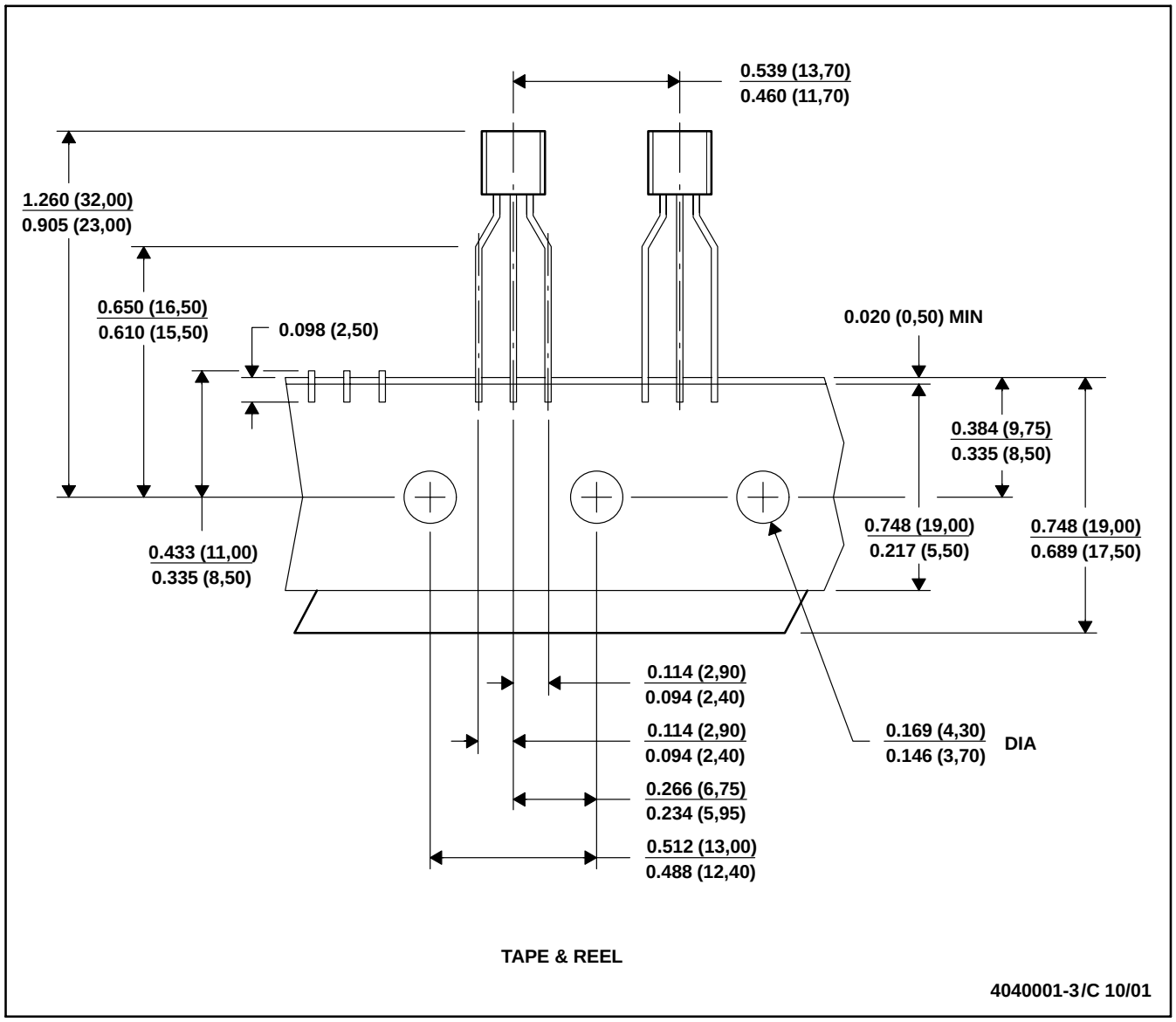
MSOT002A – OCTOBER 1994 – REVISED NOVEMBER 2001

LP (O-PBCY-W3) **PLASTIC CYLINDRICAL PACKAGE**



NOTES: A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Lead dimensions are not controlled within this area
D. FAlls within JEDEC TO -226 Variation AA (TO-226 replaces TO-92)
E. Shipping Method:
Straight lead option available in bulk pack only.
Formed lead option available in tape & reel or ammo pack.

LP (O-PBCY-W3) **PLASTIC CYLINDRICAL PACKAGE**



NOTES: A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Tape and Reel information for the Format Lead Option package.

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